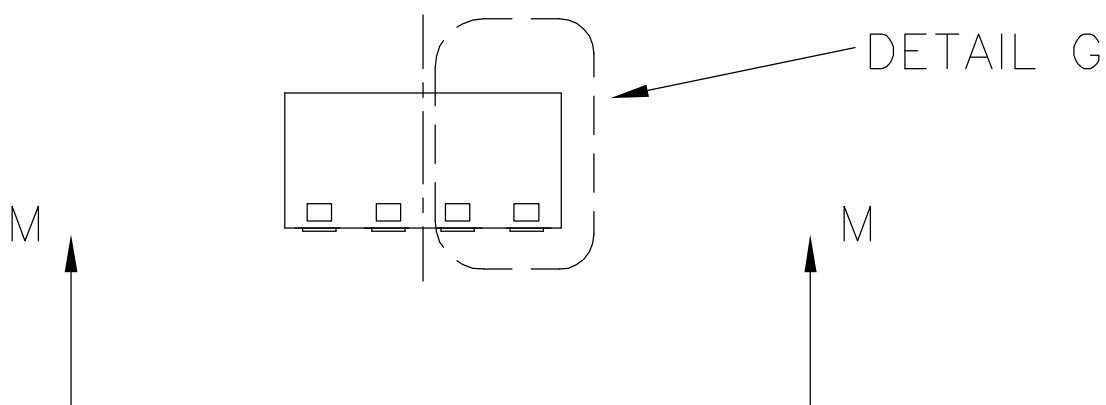
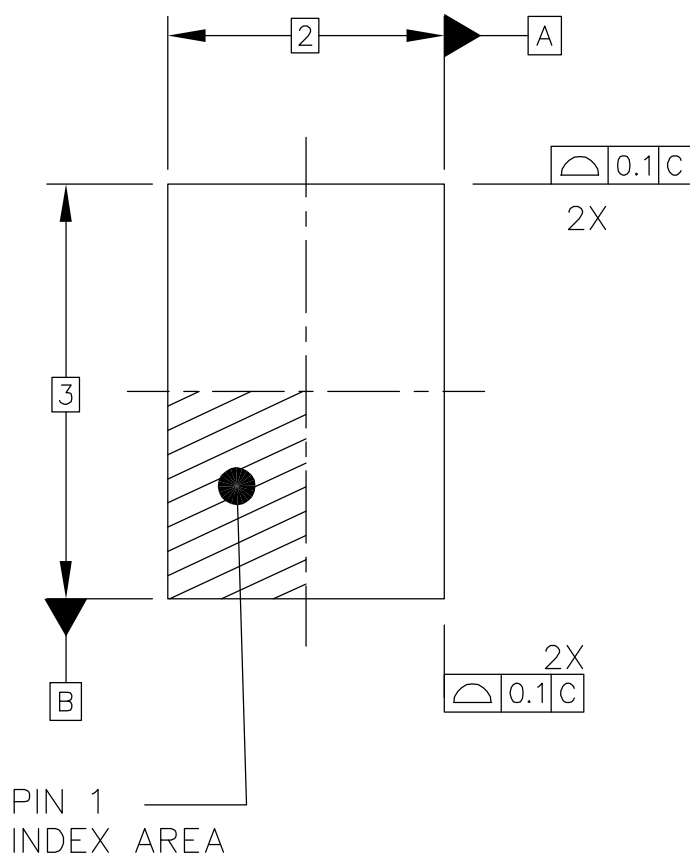




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TITLE: THERMALLY ENHANCED PLASTIC ULTRA THIN DUAL FLAT NO LEAD PACKAGE (UDFN) 8 TERMINAL, 0.5 PITCH (2 X 3 X 0.65)		DOCUMENT NO: 98ASA10774D	REV: A
		STANDARD: NON-JEDEC	
		SOT1590-1	14 MAR 2016

0.3
0.2

0.3
0.2

BACKSIDE PIN 1 INDEX

EXPOSED DIE ATTACH PAD

1.45
1.20

1 4

8X 0.100
0.015

1.05
0.80

8X 0.65
0.45

8 5

8X 0.30
0.18

0.25

6X 0.5

VIEW M-M



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PDSO-N.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2 MM EXCEPT GAP BETWEEN LEADS TO EXPOSED DIE ATTACH PAD IS 0.15 MM.

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